

FIGURE 1A

FIGURE 1B

PROVIDING A CONVENTIONAL SEMICONDUCTOR DIE AND LEADFRAME, STEP A.

DISPENSING AN INSTANT CURING ADHESIVE MATERIAL ON THE LEADFRAME (OR ALTERNATELY ON THE DIE), STEP B.

PLACING THE DIE IN CONTACT WITH THE ADHESIVE MATERIAL, STEP C.

POLYMERIZING THE ADHESIVE MATERIAL TO FORM A CURED ADHESIVE LAYER AND BOND THE DIE TO THE LEADFRAME, STEP D.

FIGURE 2

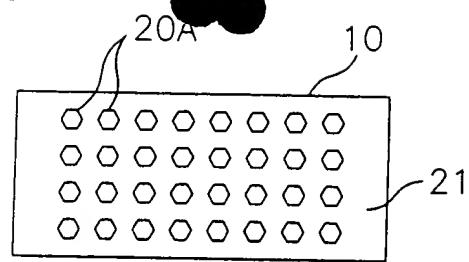


FIGURE 3A

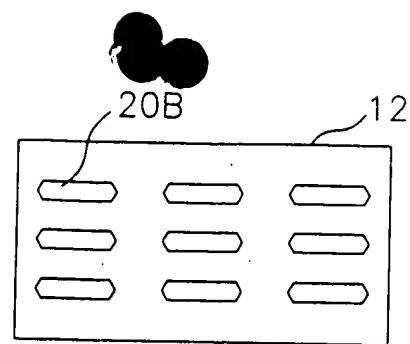


FIGURE 3B

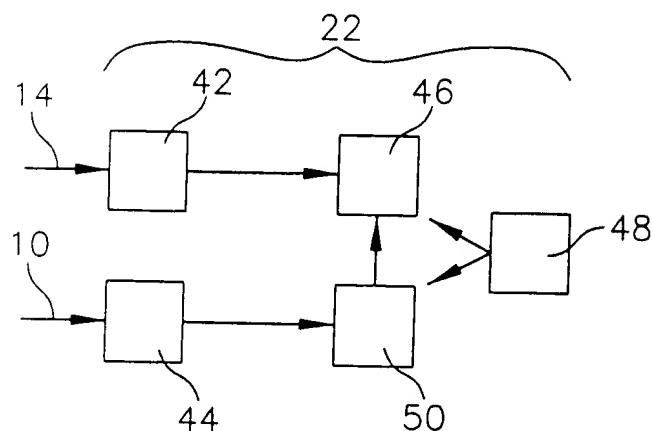


FIGURE 4

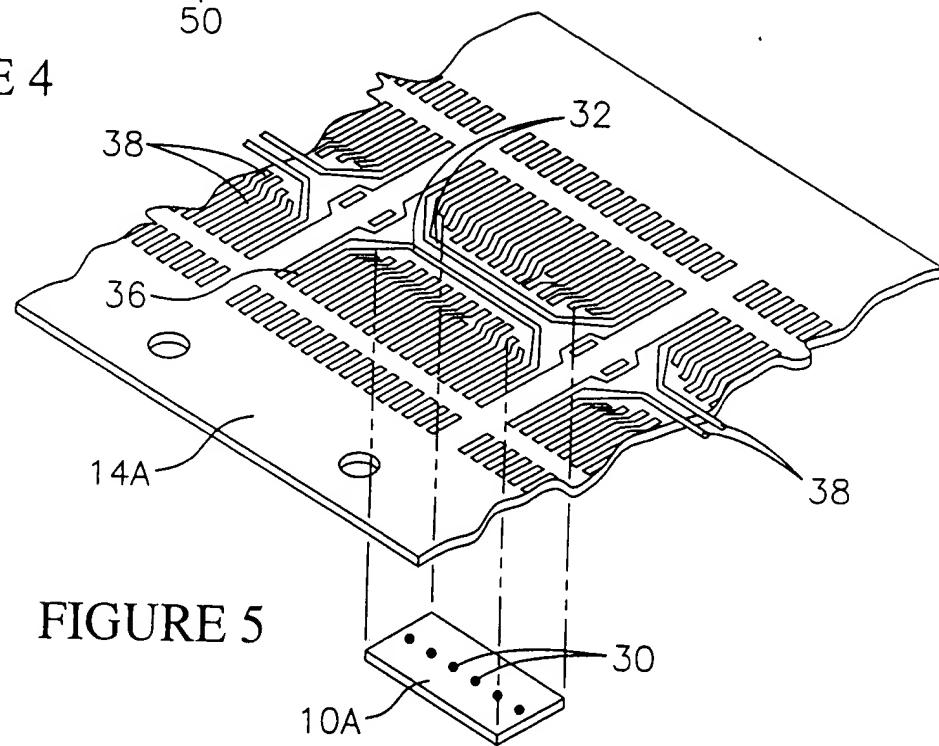


FIGURE 5

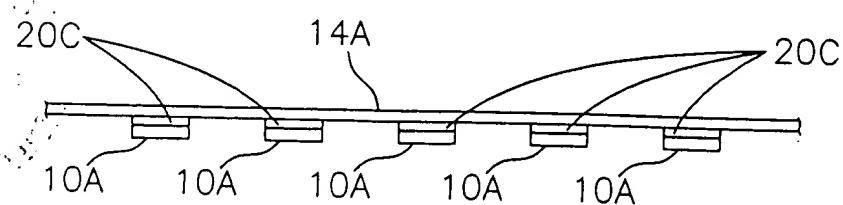


FIGURE 6